# DATA SHEET



# LDMOS FIELD EFFECT TRANSISTOR **NE55410GR**

## N-CHANNEL SILICON POWER LDMOS FET FOR 2 W + 10 W VHF to L-BAND SINGLE-END POWER AMPLIFIER

#### DESCRIPTION

The NE55410GR is an N-channel enhancement-mode LDMOS FET designed for driver 0.1 to 2.6 GHz PA, such as, cellular base station amplifier, analog/digital TV-transmitters, and the other PA's. This product has two different FET's on one die manufactured using our NEWMOS technology (our WSi gate lateral MOS FET), and its nitride surface passivation and quadruple layer aluminum silicon metalization offer a high degree of reliability.

#### FEATURES

- Two different FET's (Q1 : Pout = 2 W, Q2 : Pout = 10 W) in one package
- Over 25 dB gain available by connecting two FET's in series

		: GL (Q1) = 13.5 dB TYP. (VDS = 28 V, IDset (Q1) = 20 mA, f = 2 140 MHz)
		: GL (Q2) = 11.0 dB TYP. (VDs = 28 V, IDset (Q2) = 100 mA, f = 2 140 MHz)
•	High 1 dB compression output power	: Po (1 dB) (Q1) = 35.4 dBm TYP. (VDS = 28 V, IDset (Q1) = 20 mA, f = 2 140 MHz)
		: Po (1 dB) (Q2) = 40.4 dBm TYP. (VDS = 28 V, IDset (Q2) = 100 mA, f = 2 140 MHz)
•	High drain efficiency	: $\eta d(Q1) = 52\%$ TYP. (VDS = 28 V, IDset(Q1) = 20 mA, f = 2 140 MHz)
		: $\eta d(Q2) = 46\%$ TYP. (VDS = 28 V, IDset(Q2) = 100 mA, f = 2 140 MHz)
•	Low intermodulation distortion	: $IM_{3}$ (Q1) = -40 dBc TYP. (VDS = 28 V, IDset (Q1+Q2) = 120 mA,
		f = 2 132.5/2 147.5 MHz, Pout = 33 dBm (2 tones) )

- <R> Single Supply (VDS :  $3 V < VDS \le 32 V$ )
  - Excellent Thermal Stability
  - Surface mount type and Super low cost plastic package : 16-pin plastic HTSSOP
  - Integrated ESD protection
  - · Excellent stability against HCI (Hot Carrier Injection)

#### **APPLICATION**

- <R> Digital cellular base station PA : W-CDMA/GSM/D-AMPS/N-CDMA/PCS etc.
  - UHF-band TV transmitter PA

Caution Observe precautions when handling because these devices are sensitive to electrostatic discharge.

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Document No. PU10542EJ03V0DS (3rd edition) Date Published January 2007 NS CP(N) © NEC Electronics Corporation 2004, 2007

The mark <R> shows major revised points.

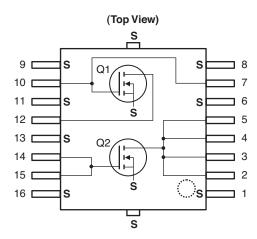
#### **ORDERING INFORMATION**

Part Number	Order Number	Package	Marking	Supplying Form
NE55410GR	NE55410GR-T3-AZ	16-pin plastic HTSSOP (Pb-Free) <sup>№te</sup>	55410	<ul> <li>Embossed tape 12 mm wide</li> <li>Pin 1 and 8 indicates pull-out direction of tape</li> <li>Qty 1 kpcs/reel</li> </ul>

**Note** With regards to terminal solder (the solder contains lead) plated products (conventionally plated), contact your nearby sales office.

**Remark** To order evaluation samples, contact your nearby sales office. Part number for sample order: NE55410GR

#### PIN CONNECTIONS AND INTERNAL BLOCK DIAGRAM



Pin No.	Pin Name	Pin No.	Pin Name
1	Source	9	Source
2	Drain (Q2)	10	Gate (Q1)
3	Drain (Q2)	11	Source
4	Drain (Q2)	12	Drain (Q1)
5	Drain (Q2)	13	Source
6	Source	14	Gate (Q2)
7	Gate (Q1)	15	Gate (Q2)
8	8 Source		Source

Remark All the terminals of a Q2 connected to a circuit. Backside : Source (S)

#### ABSOLUTE MAXIMUM RATINGS (TA = +25°C, unless otherwise specified)

Parameter	Symbol	Test Conditions	Ratings	Unit
Drain to Source Voltage	VDS		65	V
Gate to Source Voltage	Vgs		±7	V
Drain Current (Q1)	ID (Q1)		0.25	А
Drain Current (Q2)	D (Q2)		1.0	А
Total Device Dissipation (T <sub>case</sub> = 25°C)	Ptot		40	W
Input Power (Q1)	Pin (Q1)	f = 2.14 GHz, V <sub>DS</sub> = 28 V	0.3	W
Input Power (Q2)	Pin (Q2)	f = 2.14 GHz, V <sub>DS</sub> = 28 V	1.5	W
Channel Temperature	Tch		150	°C
Storage Temperature	Tstg		-65 to +150	°C

#### THERMAL RESISTANCE ( $T_A = +25^{\circ}C$ )

Parameter	Symbol	Test Conditions	MIN.	TYP.	MAX.	Unit
Channel to Case Resistance	Rth (ch-c)		-	2.5	3.0	°C/W

#### **RECOMMENDED OPERATING CONDITIONS (TA = +25°C)**

	Parameter	Symbol	MIN.	TYP.	MAX.	Unit
<r></r>	Drain to Source Voltage	Vds	-	28	32	V
	Gate to Source Voltage	Vgs	2.7	3.3	3.7	V
	Input Power (Q1), CW	Pin (Q1)	-	15	23	dBm
	Input Power (Q2), CW	Pin (Q2)	-	20	30	dBm
<r></r>	Average Output Power (Q1), CW Note	PO (ave.) (Q1)	-	-	24	dBm
<r></r>	Average Output Power (Q2), CW Note	PO (ave.) (Q2)	_	_	30	dBm

<R> Note When mounting on the PWB that our company recommends.

### ELECTRICAL CHARACTERISTICS (T<sub>A</sub> = +25°C)

Parameter	Symbol	Test Conditions	MIN.	TYP.	MAX.	Unit	
Q1							
Gate to Source Leak Current	IGSS (Q1)	V <sub>GSS</sub> = 5V	-	-	1	μA	
Drain to Source Leakage Current	IDSS (Q1)	VDSS = 65 V	-	-	1	mA	
Gate Threshold Voltage	Vth (Q1)	V <sub>DS</sub> = 10 V, I <sub>DS</sub> = 1 mA	2.2	2.8	3.4	V	
Transconductance	<b>g</b> m (Q1)	V <sub>DS</sub> = 28 V, I <sub>DS</sub> = 20 mA	-	0.09	-	S	
Drain to Source Breakdown Voltage	BVDSS (Q1)	loss = 10 μA	65	75	-	V	
Q2							
Gate to Source Leak Current	IGSS (Q2)	V <sub>GSS</sub> = 5V	-	-	1	μA	
Drain to Source Leakage Current	IDSS (Q2)	VDSS = 65 V	-	-	1	mA	
Gate Threshold Voltage	Vth (Q2)	V <sub>DS</sub> = 10 V, I <sub>DS</sub> = 1 mA	2.0	2.6	3.2	V	
Transconductance	<b>g</b> m (Q2)	Vps = 28 V, lps = 100 mA	-	0.45	-	S	
Drain to Source Breakdown Voltage	BVDSS (Q2)	loss = 10 μA	65	75	-	V	

#### <R> RF CHARACTERISTICS (TA = +25°C)

Parameter	Symbol	Test Conditions	MIN.	TYP.	MAX.	Unit
Q1					·	
Gain 1 dB Compression Output Power	<b>P</b> O (1 dB)	f = 2 140 MHz, V <sub>DS</sub> = 28 V,	-	35.4	-	dBm
Drain Efficiency	$\eta_{ extsf{d}}$	I <sub>Dset</sub> = 20 mA	-	52	-	%
Linear Gain	GL <sup>Note1</sup>		12	13.5	-	dB
Q2						
Gain 1 dB Compression Output Power	<b>P</b> O (1 dB)	f = 2 140 MHz, V <sub>DS</sub> = 28 V,	-	40.4	-	dBm
Drain Efficiency	$\eta_{ m d}$	I <sub>Dset</sub> = 100 mA	-	46	-	%
Linear Gain	GL <sup>Note2</sup>		9.5	11	-	dB
Gain 1 dB Compression Output Power	<b>P</b> O (1 dB)	f = 1 840 MHz, V <sub>DS</sub> = 28 V,	-	40.5	-	dBm
Drain Efficiency	$\eta_{ m d}$	I <sub>Dset</sub> = 100 mA	-	49	-	%
Linear Gain	GL <sup>Note2</sup>		-	14	-	dB
Q1 + Q2						
Gain 1 dB Compression Output Power	<b>P</b> O (1 dB)	f = 880 MHz, V <sub>DS</sub> = 28 V,	-	41.5	-	dBm
Drain Efficiency	$\eta_{ m d}$	I <sub>Dset</sub> = 120 mA (Q1 + Q2)	-	55	-	%
Linear Gain	GL <sup>Note3</sup>		-	30	-	dB
Gain 1 dB Compression Output Power	<b>P</b> O (1 dB)	f = 2 140 MHz, V <sub>DS</sub> = 28 V,	-	40.0	-	dBm
Drain Efficiency	$\eta_{ m d}$	I <sub>Dset</sub> = 120 mA (Q1 + Q2)	34	42	-	%
Output Power	Pout		39	40	-	dB
Linear Gain	GL <sup>Note4</sup>		24	25	-	dB
3rd Order Intermodulation Distortion	IМз	f = 2 132.5/2 147.5 MHz, V <sub>DS</sub> = 28 V,	-	-40	-	dBc
Drain Efficiency	$\eta_{ m d}$	2 carrier W-CDMA 3GPP, Test Model1, 64DPCH, 67% Clipping, I <sub>Dset</sub> = 120 mA (Q1 + Q2), Ave P <sub>out</sub> = 33 dBm	_	21	-	%

**Notes 1.** P<sub>in</sub> = 15 dBm

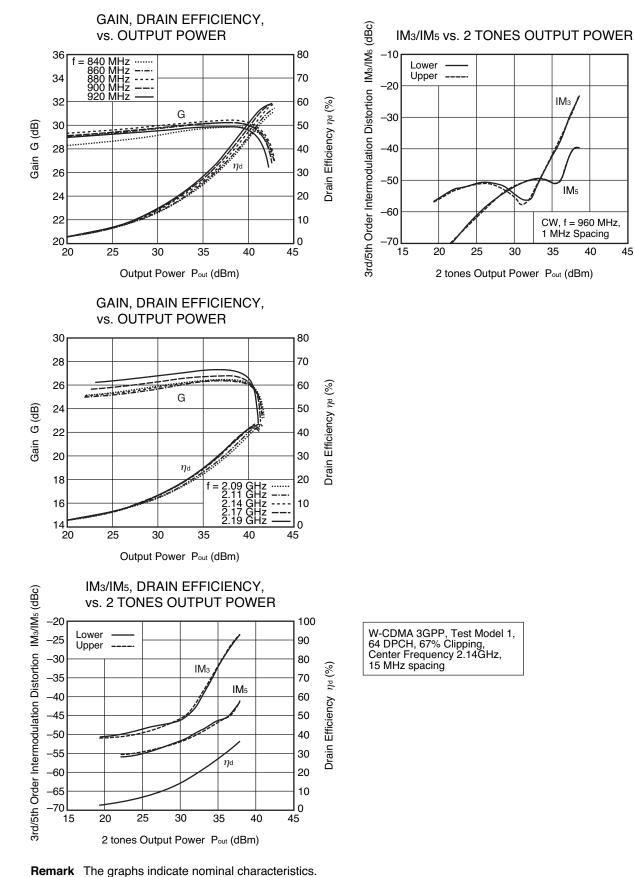
**2.**  $P_{in} = 20 \text{ dBm}$ 

**3.**  $P_{in} = 5 \text{ dBm}$ 

**4.**  $P_{in} = 10 \text{ dBm}$ 

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#### TYPICAL CHARACTERISTICS (TA = +25°C, VDs = 28 V, IDset = 120 mA, unless otherwise specified)

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#### <R> S-PARAMETERS

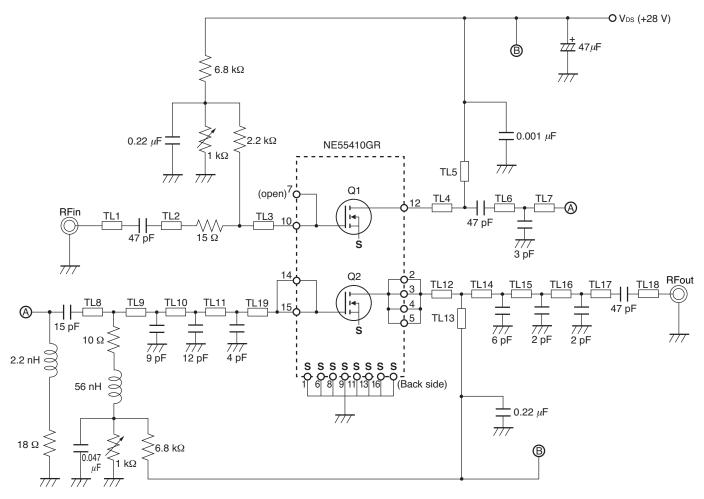
S-parameters/Noise parameters are provided on our web site in a form (S2P) that enables direct import to a microwave circuit simulator without keyboard input.

Click here to download S-parameters.

[RF and Microwave]  $\rightarrow$  [Device Parameters]

URL http://www.ncsd.necel.com/microwave/index.html

#### EVALUATION CIRCUIT (f = 840 to 960 MHz, VDs = 28 V, IDset = 120 mA)

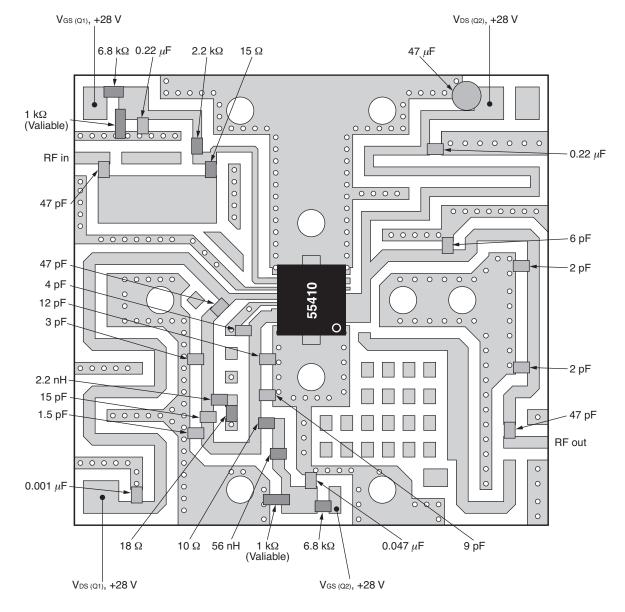


Symbol	Width (mm)	Length (mm)	
TL1	1.0	3.0	
TL2	4.5	10.0	
TL3	0.5	16.0	
TL4	0.5	5.0	
TL5	1.0	48.0	
TL6	1.0	4.0	
TL7	1.0	3.0	
TL8	1.0	6.0	
TL9	1.0	3.0	
TL10	1.0	4.0	

Symbol	Width (mm)	Length (mm)
TL11	1.0	3.0
TL12	1.0	5.0
TL13	0.8	48.0
TL14	1.0	6.5
TL15	1.0	10.5
TL16	1.0	9.5
TL17	1.0	10.0
TL18	1.0	6.0
TL19	1.0	3.0

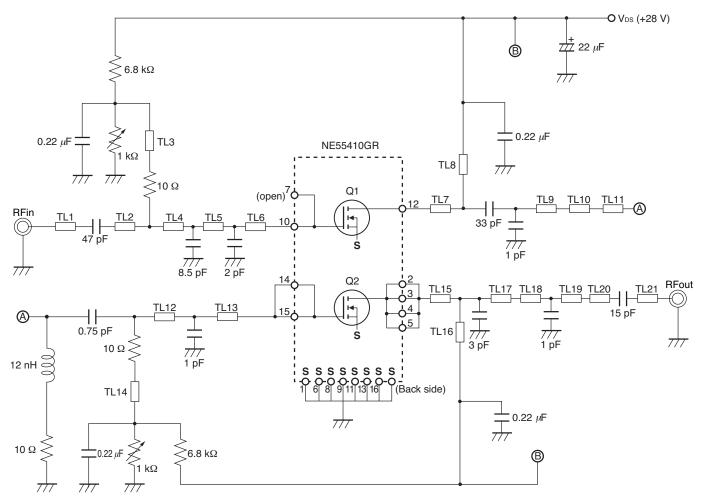
The application circuits and their parameters are for reference only and are not intended for use in actual design-ins.

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#### EVALUATION CIRCUIT (f = 840 to 960 MHz, VDs = 28 V, IDset = 120 mA)

EVALUATION CIRCUIT (f = 2 090 to 2 190 MHz, VDs = 28 V, IDset = 120 mA)



C						
Symbol	Width (mm)	Length (mm)		Symbol	Width (mm)	Length (mm)
TL1	1.0	17.0		TL12	1.0	4.0
TL2	1.0	4.0		TL13	1.0	4.5
TL3	1.0	24.5		TL14	1.0	25.0
TL4	1.0	2.5		TL15	2.5	2.5
TL5	1.0	3.0		TL16	1.0	27.0
TL6	0.5	2.5		TL17	1.0	2.0
TL7	0.5	4.5		TL18	5.0	4.0
TL8	1.0	25.5		TL19	5.0	2.0
TL9	1.0	2.5		TL20	1.0	12.5
TL10	4.5	4.5		TL21	1.0	5.5
TL11	1.0	3.5	'			

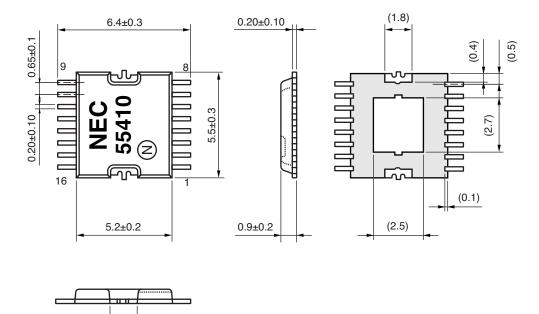
The application circuits and their parameters are for reference only and are not intended for use in actual design-ins.

#### 1 kΩ (Potentiometer) VDS (Q2), +28 V $V_{\text{GS}\,(\text{Q1})},\,\text{+28}\,\,V$ 6.8 kΩ 0.22 μF Ω 22 μF 0 0 0 0 0 ,0.22 μF C 0 0 0 0 0 0 0 0 0 0 RF in 15 pF 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 С 0.5 pF 2 pF 0 0 0 33 pF 3 pF 1 pF 0 0 1.0 pF -0 0 $\left( \right)$ 0 0 0 RF out 0.22 μF C 12 nH Ω 0 0 0 15 pF 1 pF 0.22 μF $1 k\Omega$ 6.8 kΩ 0.75 pF Ω (Potentiometer) VGS (Q2), +28 V VDS (Q1), +28 V

#### <R> EVALUATION CIRCUIT (f = 2 090 to 2 190 MHz, VDs = 28 V, IDset = 120 mA)

#### PACKAGE DIMENSIONS

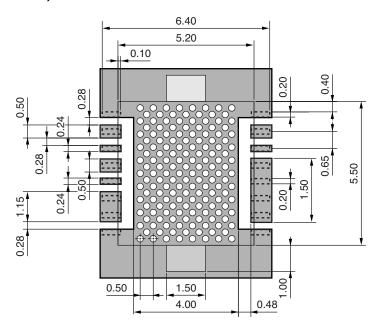
#### 16-PIN PLASTIC HTSSOP (UNIT: mm)





(1.5)

#### LAND PATTERN (UNIT: mm)



#### Remarks1. Via holes : 158 holes

- **2.** Hole size :  $\phi$  0.15 mm
  - 3. Min. spacing : 0.354 mm
  - 4. Solder resist or etching

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#### **RECOMMENDED SOLDERING CONDITIONS**

This product should be soldered and mounted under the following recommended conditions. For soldering methods and conditions other than those recommended below, contact your nearby sales office.

Soldering Method	Soldering Conditions		Condition Symbol
Infrared Reflow	Peak temperature (package surface temperature) Time at peak temperature Time at temperature of 220°C or higher Preheating time at 120 to 180°C Maximum number of reflow processes Maximum chlorine content of rosin flux (% mass)	: 260°C or below : 10 seconds or less : 60 seconds or less : 120±30 seconds : 3 times : 0.2%(Wt.) or below	IR260
Wave Soldering	Peak temperature (molten solder temperature) Time at peak temperature Preheating temperature (package surface temperature) Maximum number of flow processes Maximum chlorine content of rosin flux (% mass)	: 260°C or below : 10 seconds or less : 120°C or below : 1 time : 0.2%(Wt.) or below	WS260
Partial Heating	Peak temperature (terminal temperature) Soldering time (per side of device) Maximum chlorine content of rosin flux (% mass)	: 350°C or below : 3 seconds or less : 0.2%(Wt.) or below	HS350

Caution Do not use different soldering methods together (except for partial heating).

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Lead (Pb)	< 1000 PPM	-A Not Detected	-AZ (*)
Mercury	< 1000 PPM	Not Detected	
Cadmium	< 100 PPM	Not Detected	
Hexavalent Chromium	< 1000 PPM	Not Detected	
РВВ	< 1000 PPM	Not Detected	
PBDE	< 1000 PPM	Not Detected	

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